



4 Layer Stackup Documentation

Layer	Base CU / Plt	Thick	Type	Stackup	Subs	Imp	Material
Silkscreen		0.00					Taiyo-SS - White
Soldermask		0.60					Taiyo-SM - Red
Lyr1	0.5oz / Std	1.80	S				
Prepreg		7.04					370HR - 2x2113_59%
Lyr2	1oz	1.20	S				
Core		39.00					370HR - 39.0mils
Lyr3	1oz	1.20	S				
Prepreg		7.04					370HR - 2x2113_59%
Lyr4	0.5oz / Std	1.80	S				
Soldermask		0.60					Taiyo-SM - Red
Silkscreen		0.00					Taiyo-SS - White

Required Thickness

Type	Req. Thick	Tol% +	Tol% -	Act. Thick	Measured
Overall	62.0	10.0	10.0	60.3	
Over lamination	62.0	10.0	10.0	56.7	
Over laminate	62.0	10.0	10.0	55.5	
Over metal	62.0	10.0	10.0	59.1	

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